

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yi-Chun Lin</td> <td>03/28/2007</td> </tr> <tr> <td>Chi-Chih Chen</td> <td>03/28/2007</td> </tr> <tr> <td>Kuo-Ming Wu</td> <td>03/28/2007</td> </tr> <tr> <td>Ruey-Hsin Liu</td> <td>03/28/2007</td> </tr> </tbody> </table>		Name	Execution Date	Yi-Chun Lin	03/28/2007	Chi-Chih Chen	03/28/2007	Kuo-Ming Wu	03/28/2007	Ruey-Hsin Liu	03/28/2007
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RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.										
Street Address:	No. 8, Li-Hsin Rd. 6										
Internal Address:	Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77, R.O.C.										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11692213</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11692213						
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Application Number:	11692213										
CORRESPONDENCE DATA											
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ATTORNEY DOCKET NUMBER:	252011-4250										
NAME OF SUBMITTER:	Daniel R. McClure										

OP \$40.00 11692213

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Yi-Chun LIN, Chi-Chih CHEN, Kuo-Ming WU and Ruey-Hsin LIU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: HIGH VOLTAGE SEMICONDUCTOR DEVICES AND METHODS FOR FABRICATING THE SAME

Filed: _____ Serial No. _____

Executed on: March 28, 2007

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Yi-Chun LIN

Yi-Chun LIN

2007 / 3 / 28

Date:

Chi-Chih Chen

Chi-Chih CHEN

2007. 3. 28

Date:

Kuo-Ming WU

Kuo-Ming WU

2007. 3. 28

Date:

Ruey-Hsin LIU

Ruey-Hsin LIU

2007. 3. 28

Date: